

EMIPAK 2B PressFit Power Module 3-Levels Half Bridge Inverter Stage, 150 A



EMIPAK-2B
(package example)



RoHS
COMPLIANT

FEATURES

- Trench IGBT technology
- FRED Pt® clamping diodes
- PressFit pins technology
- Exposed Al₂O₃ substrate with low thermal resistance
- Short circuit rated
- Square RBSOA
- Integrated thermistor
- Low internal inductances
- Low switching loss
- PressFit pins locking technology. Patent # US.263.820 B2
- UL approved file E78996
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

VS-ETF150Y65N is an integrated solution for a multi level inverter stage in a single package. The EMIPAK 2B package is easy to use thanks to the PressFit pins and the exposed substrate provides improved thermal performance. The optimized layout also helps to minimize stray parameters, allowing for better EMI performance.

PRIMARY CHARACTERISTICS	
Q1 to Q4 IGBT	
V _{CES}	650 V
V _{CE(on)} typical at I _C = 150 A	1.70 V
I _C at T _C = 82 °C	150 A
Speed	8 kHz to 30 kHz
Package	EMIPAK 2B
Circuit configuration	3-levels half bridge inverter stage

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Operating junction temperature	T _J		175	°C
Storage temperature range	T _{Stg}		-40 to +150	
RMS isolation voltage	V _{ISOL}	T _J = 25 °C, all terminals shorted, f = 50 Hz, t = 1 s	3500	V
Q1 to Q4 IGBT				
Collector to emitter voltage	V _{CES}		650	V
Gate to emitter voltage	V _{GES}		20	
Pulsed collector current	I _{CM}		450	A
Clamped inductive load current	I _{LM}		180	
Continuous collector current	I _C	T _C = 25 °C	201	A
		T _C = 60 °C	171	
		T _{SINK} = 60 °C	77	
Power dissipation	P _D	T _C = 25 °C	600	W
		T _C = 60 °C	460	
D5 - D6 CLAMPING DIODE				
Repetitive peak reverse voltage	V _{RPM}		650	V
Single pulse forward current	I _{FSM}	10 ms sine or 6 ms rectangular pulse, T _J = 25 °C	750	A
Diode continuous forward current	I _F	T _C = 25 °C	161	
		T _C = 60 °C	140	
		T _{SINK} = 60 °C	74	
Power dissipation	P _D	T _C = 25 °C	319	W
		T _C = 60 °C	245	

PATENT(S): www.vishay.com/patents

This Vishay product is protected by one or more United States and International patents.



ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
D1 - D2 - D3 - D4 AP DIODE				
Single pulse forward current	I_{FSM}	10 ms sine or 6 ms rectangular pulse, $T_J = 25\text{ }^\circ\text{C}$	500	A
Diode continuous forward current	I_F	$T_C = 25\text{ }^\circ\text{C}$	102	
		$T_C = 60\text{ }^\circ\text{C}$	92	
Power dissipation	P_D	$T_C = 25\text{ }^\circ\text{C}$	238	W
		$T_C = 60\text{ }^\circ\text{C}$	182	

Notes

- Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur
- (1) $V_{CC} = 325\text{ V}$, $V_{GE} = 15\text{ V}$, $L = 500\text{ }\mu\text{H}$, $R_g = 4.7\text{ }\Omega$, $T_J = 175\text{ }^\circ\text{C}$

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Q1 to Q4 IGBT						
Collector to emitter breakdown voltage	BV_{CES}	$V_{GE} = 0\text{ V}$, $I_C = 100\text{ }\mu\text{A}$	650	-	-	V
Collector to emitter voltage	$V_{CE(on)}$	$V_{GE} = 15\text{ V}$, $I_C = 150\text{ A}$	-	1.70	2.17	
		$V_{GE} = 15\text{ V}$, $I_C = 150\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$	-	1.95	-	
Gate threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$, $I_C = 5.0\text{ mA}$	5.0	6.0	8.4	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T_J$	$V_{CE} = V_{GE}$, $I_C = 1.0\text{ mA}$ ($25\text{ }^\circ\text{C}$ to $125\text{ }^\circ\text{C}$)	-	-18	-	mV/ $^\circ\text{C}$
Forward transconductance	g_{fe}	$V_{CE} = 20\text{ V}$, $I_C = 150\text{ A}$	-	102	-	S
Transfer characteristics	V_{GE}	$V_{CE} = 20\text{ V}$, $I_C = 150\text{ A}$	-	10.2	-	V
Zero gate voltage collector current	I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = 650\text{ V}$	-	0.1	100	μA
		$V_{GE} = 0\text{ V}$, $V_{CE} = 650\text{ V}$, $T_J = 125\text{ }^\circ\text{C}$	-	130	-	
Gate to emitter leakage current	I_{GES}	$V_{GE} = \pm 20\text{ V}$, $V_{CE} = 0\text{ V}$	-	-	± 600	nA
D5 - D6 CLAMPING DIODE						
Cathode to anode blocking voltage	V_{BR}	$I_R = 500\text{ }\mu\text{A}$	650	-	-	V
Forward voltage drop	V_{FM}	$I_F = 100\text{ A}$	-	1.64	2.2	
		$I_F = 100\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$	-	1.35	-	
Reverse leakage current	I_{RM}	$V_R = 650\text{ V}$	-	0.3	100	μA
		$V_R = 650\text{ V}$, $T_J = 125\text{ }^\circ\text{C}$	-	100	-	
D1 - D2 - D3 - D4 AP DIODE						
Forward voltage drop	V_{FM}	$I_F = 100\text{ A}$	-	2.1	2.9	V
		$I_F = 100\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$	-	1.64	-	

SWITCHING CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Q1 to Q4 IGBT						
Total gate charge (turn-on)	Q_g	$I_C = 150\text{ A}$ $V_{CC} = 400\text{ V}$ $V_{GE} = 15\text{ V}$	-	310	-	nC
Gate to emitter charge (turn-on)	Q_{ge}		-	95	-	
Gate to collector charge (turn-on)	Q_{gc}		-	130	-	
Input capacitance	C_{ies}	$V_{GE} = 0\text{ V}$ $V_{CC} = 30\text{ V}$ $f = 1\text{ MHz}$	-	9900	-	pF
Output capacitance	C_{oes}		-	460	-	
Reverse transfer capacitance	C_{res}		-	250	-	